

CLAIMS

1 1. A method of providing thermal connection between a
2 cooling device and a device to be cooled, the method comprising:

3 a. applying an adhesive to a thermal interface outside a
4 heat transfer area of the thermal interface;

5 b. attaching the thermal interface to the cooling device;
6 and

7 c. attaching the device to be cooled to the thermal
8 interface.

1 2. The method of claim 1 wherein said adhesive includes a
2 pressure sensitive adhesive (PSA).

1 3. The method of claim 1 wherein said cooling device
2 includes a heat sink device.

1 4. The method of claim 1 wherein said cooling device
2 includes a thermal plate.

1 5. The method of claim 1 wherein said device to be cooled
2 includes an integrated circuit package.

1 6. The method of claim 1 wherein said adhesive is applied
2 at a periphery of said thermal interface.

1 7. The method of claim 1 wherein said thermal interface
2 includes a Chomerics T443 film.

4 an adhesive applied to the first surface outside the heat
5 transfer area;

6 a cooling device attached to the thermal interface at said
7 first surface thereof; and

8 a device to be cooled attached at said second surface of
9 the thermal interface.

1 16. The apparatus of claim 15 wherein said adhesive
2 includes a pressure sensitive adhesive (PSA).

1 17. The apparatus of claim 15 wherein said cooling device
2 includes a heat sink.

1 18. The apparatus of claim 15 wherein said device to be
2 cooled includes an integrated circuit package.

1 19. The apparatus of claim 15 wherein said device to be
2 cooled includes a thermal plate.